L Number	Hits	Search Text	DB	Time stamp
309	11	("3191100" | "3457639" | "3516155" | "3540121" | "3648121" | "3931922" | "4371912" | "4698662" | "4957882" | "4979289" | "5182632").PN.	USPAT	2003/07/21 13:47
310	6	5561328.URPN.	USPAT	2003/07/21 13:49
386	9037	(die or ic or integrated adj circuit or chip) near2 (alignment or align or aligning or positioning or position or placement or placing or placed or place or locating or location or locater or aligner or positioner or attach or attachment or attaching or attached or affixing or affixed or affix) near5 (frame or template or socket or grid or opening or aperture or matrix)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/21 13:58
387	405	(die or chip) adj (alignment or align or aligning or positioning or position or placement or placing or placed or place or locating or location or locater or aligner or positioner or attach or attachment or attaching or attached or affixing or affixed or affix) near3 (frame or template or socket or grid or opening or aperture or matrix) and (optical near2 circuit or oic or laser or led or oled or mirror)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/21 14:48
388	320	(die or chip) adj (alignment or align or aligning or positioning or position or placement or placing or placed or place or locating or location or locater or aligner or positioner or attach or attachment or attaching or attached or affixing or affixed or affix) near3 (frame or template or socket or grid or matrix) and (optical near2 circuit or oic or laser or led or oled or mirror)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/21 14:00
389	208	(die or chip) adj (alignment or align or aligning or positioning or position or placement or placing or placed or place or locating or location or locater or aligner or positioner or attach or attachment or attaching or attached or affixing or affixed or affix) near2 (frame or template or socket or grid or matrix) and (optical near2 circuit or oic or laser or led or oled or mirror)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/21 14:05
393	199	(die or chip) adj (alignment or align or aligning or positioning or position or placement or placing or placed or place or locating or location or locater or aligner or positioner or attach or attachment or attaching or attached or affixing or affixed or affix) near2 (frame or template or socket or grid or matrix) and (optical near2 circuit or oic or laser or light near2 diode or oled or mirror)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/21 14:06
394	4	(US-6285064-$ or US-6209532-$ or US-5890599-$ or US-5561328-$).did.	USPAT	2003/07/21 14:38
395	955	257/676.ccls.	USPAT	2003/07/21 14:38
396	150	257/676.ccls. and (LED or oic or oled or laser or light near2 emitting or optical near2 circuit or photonic near2 circuit)	USPAT	2003/07/21 14:41
397	36	(die or chip) adj (alignment or align or aligning or positioning or position or placement or placing or placed or place or locating or location or locater or aligner or positioner or attach or attachment or attaching or attached or affixing or affixed or affix) near3 (frame or template or socket or grid or matrix) near5 (opening or aperture or depression or divot or recess or recessed or depressed)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/21 14:55

398	784	257/433.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/21 14:55
399	235	257/433.ccls. and (alignment or aligned or aligning or positioning or placement)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/21 14:57
400	116	257/433.ccls. and (aperture or opening or recess or recessed or template or frame or matrix or grid) near5 (opening or aperture or recess or recessed or wall or protrusion or protruding or projection or projecting or depression or divot)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/21 15:11
401	633	mems and (micromirror or mirror) near2 (array or panel)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/21 15:22
402	192	mems and (micromirror or mirror) near2 (array or panel) and (die or array) near4 (alignment or aligning or aligned or placement or positioning or placing or positioned)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/21 15:24
403	119	mems and (micromirror or mirror) near2 (array or panel) and (die or array) near2 (alignment or aligning or aligned or placement or positioning or placing or positioned)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/21 15:31
-	1228	(MEMS or (micromirror or mirror) near2 (array or subarray)) same (package or packaging or housing)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/21 09:34
-	784	(MEMS or (micromirror or mirror) near2 (array or subarray)) with (package or packaging or housing)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/21 09:34
-	186	((micromirror or mirror) near2 (array or subarray)) with (package or packaging or housing)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/21 10:32
-	13627	(die or ic or integrated adj circuit or chip) near6 (alignment or align or aligning or positioning or position or placement or placing or placed or place or locating or location or locater or aligner or positioner) near10 (aperture or hole or wall or projection or protrusion or depression or divot or grid or template)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/21 10:38
-	807	(die or ic or integrated adj circuit or chip) near4 (alignment or align or aligning or positioning or position or placement or placing or placed or place or locating or location or locater or aligner or positioner) near4 (aperture or hole or wall or projection or protrusion or depression or divot or grid or template) and (package or packaging or housing) and (mirror or mems or optical adj ic or optical near2 circuit or laser or diode or led or oled)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/21 10:42

-	485	(die or ic or integrated adj circuit or chip) near4 (alignment or align or aligning or positioning or position or placement or placing or placed or place or locating or location or locater or aligner or positioner) near4 (aperture or hole or wall or projection or protrusion or depression or divot or grid or template) and (die or ic or integrated adj circuit or chip) near4 (mount or mounted or mounting or attach or attaching or attachment or attached or adhere or adhered or adhering or affixing or affix or affixed) and (substrate or wafer or lead adj frame) and (package or packaging or housing) and (mirror or mems or optical adj ic or optical near2 circuit or laser or diode or led or oled)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/21 11:42
-	1415	(die or ic or integrated adj circuit or chip) near4 (alignment or align or aligning or positioning or position or placement or placing or placed or place or locating or location or locater or aligner or positioner) near8 (template or matrix or grid)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/21 11:43
-	486	(die or ic or integrated adj circuit or chip) near4 (alignment or align or aligning or positioning or position or placement or placing or placed or place or locating or location or locater or aligner or positioner) near5 (template or matrix or grid) and (housing or package or packaging)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/21 12:02
-	471	(die or ic or integrated adj circuit or chip) near4 (alignment or align or aligning or positioning or position or placement or placing or placed or place or locating or location or locater or aligner or positioner) near5 (template or matrix or grid) and (housing or package or packaging) not bump adj placement not power adj grid	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/21 12:11
-	331	(die or ic or integrated adj circuit or chip) near4 (alignment or align or aligning or positioning or position or placement or placing or placed or place or locating or location or locater or aligner or positioner) near5 (template or matrix or grid) and (housing or package or packaging) not bump adj placement not power adj grid not ball adj grid	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/21 13:04
-	772	(die or ic or integrated adj circuit or chip) near4 (alignment or align or aligning or positioning or position or placement or placing or placed or place or locating or location or locater or aligner or positioner) near5 (socket) and (housing or package or packaging)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/21 13:03
-	316	(die or ic or integrated adj circuit or chip) near4 (alignment or align or aligning or positioning or position or placement or placing or placed or place or locating or location or locater or aligner or positioner) near5 (template or matrix or grid) and (housing or package or packaging) not bump adj placement not power adj grid not ball adj grid not microfluid$ not fluid$ near3 filter$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/21 13:55